

JFP PP6 Rework & Die Bonder Station



The machines which require minimal training to operate

▶ XYZ Automated process

MADE IN FRANCE



- The model PP6 Rework Station is designed for accurate Die Removal, Bond Area Planner, Solder Balls Removal and Local Vacuum Cleaner, with outstanding accurate placement capability of delicate devices on substrate or deep Packages. (Optional Flip).
- Pick and Place from Wafer, from Waffle Pack, Gel-Pak or bulk Die media.
- PP6 Rework Station achieves a placement accuracy better than $<5\mu\text{m}$.
- Efficient die remover system, with dual action, including local Hot Gaz and adjustable shear effect, compatible with very small Dies ($<200\mu\text{m}$), in very high-density Hybrid Devices.
- Adjustable routine for solder ball removal, for surface planner and vacuum cleaner.
- A robust, and reliable mechanical concept, designed to be external vibration free.
- Easy to use, flexible, the PP6 Rework Station requires only minimum training to operate.

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APPLICATIONS

- Rework Small Chips
- Placement of delicate Devices

SYSTEM

- PC & Microcontroller
- Frame

DIE & SUBSTRATE

- Minimum die size 150*200µm
- Maximum die size 20*20mm
- Substrate Up to 300 mm standard

VISION SYSTEM

- Video Microscope UHD cameras, 18Mp
- Full std FOV = 2,7mm
Std Pixel resolution 1p = 0,55µm
Other magnification (FOV) on request
- Digital Zoom x 10
- Monitor : TFT 22"
- Led Lighting, co-axial and oblique

REWORK

- Hot Gas Gun

MOTORIZED XY TABLES

- Motorized X 260mm, Y 120mm
step resolution 0,23µm
Display Unit : 1µm
- Joystick control

WORKHOLDER

- Compatible for any package up to 100mm
- Customized

PARAMETERS & DISPLAY

- Friendly Graphic user Interface, GUI Menu
- Programmable force : up to 700 gr
- Programmable bond time
- Programmable scrub
- Programmable temperature ramp-up
- Programmable sequence

ALIGNMENT MODE

- Direct placement of Face-up devices
- 2 references points for auto-centering placement
- Indexed Pick and multi-Placement mode

OPTIONS

- Flip Chip alignment, Face down
- Eutectic Chuck,+ Gas environment
25°C to 450°C
- Additional Force : up to 5kg
- Sorter: Eject system for wafer
- UV Insolator

FEATURES

Placement accuracy <+/- 1µm
Vibration free
Product speed 10-50 upon Process

TECHNICAL SPECIFICATION

Power	230VAC-1kwatt
Vacuum	70%
Dimensions	650*820*1450mm
Weight	90kg